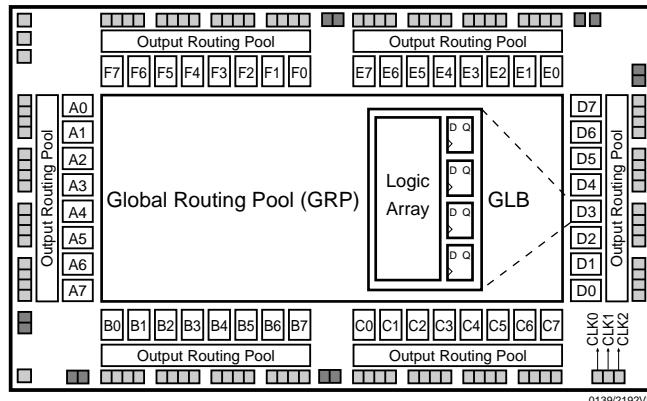


Features

- SuperFAST HIGH DENSITY IN-SYSTEM PROGRAMMABLE LOGIC
 - 8000 PLD Gates
 - 96 I/O Pins, Nine Dedicated Inputs
 - 192 Registers
 - High Speed Global Interconnect
 - Wide Input Gating for Fast Counters, State Machines, Address Decoders, etc.
 - Small Logic Block Size for Random Logic
 - Pinout Compatible with ispLSI 2096V and 2096VE
- 2.5V LOW VOLTAGE ARCHITECTURE
 - Interfaces with Standard 3.3V Devices (Inputs and I/Os are 3.3V Tolerant)
 - 175 mA Typical Active Current
- HIGH PERFORMANCE E²CMOS® TECHNOLOGY
 - $f_{max} = 150$ MHz Maximum Operating Frequency
 - $t_{pd} = 6.0$ ns Propagation Delay
 - Electrically Erasable and Reprogrammable
 - Non-Volatile
 - 100% Tested at Time of Manufacture
 - Unused Product Term Shutdown Saves Power
- IN-SYSTEM PROGRAMMABLE
 - 2.5V In-System Programmability (ISP™) Using Boundary Scan Test Access Port (TAP)
 - Open-Drain Output Option for Flexible Bus Interface Capability, Allowing Easy Implementation of Wired-OR Bus Arbitration Logic
 - Increased Manufacturing Yields, Reduced Time-to-Market and Improved Product Quality
 - Reprogram Soldered Devices for Faster Prototyping
- 100% IEEE 1149.1 BOUNDARY SCAN TESTABLE
- THE EASE OF USE AND FAST SYSTEM SPEED OF PLDs WITH THE DENSITY AND FLEXIBILITY OF FPGAs
 - Enhanced Pin Locking Capability
 - Three Dedicated Clock Input Pins
 - Synchronous and Asynchronous Clocks
 - Programmable Output Slew Rate Control
 - Flexible Pin Placement
 - Optimized Global Routing Pool Provides Global Interconnectivity

Functional Block Diagram



0139/2192VL

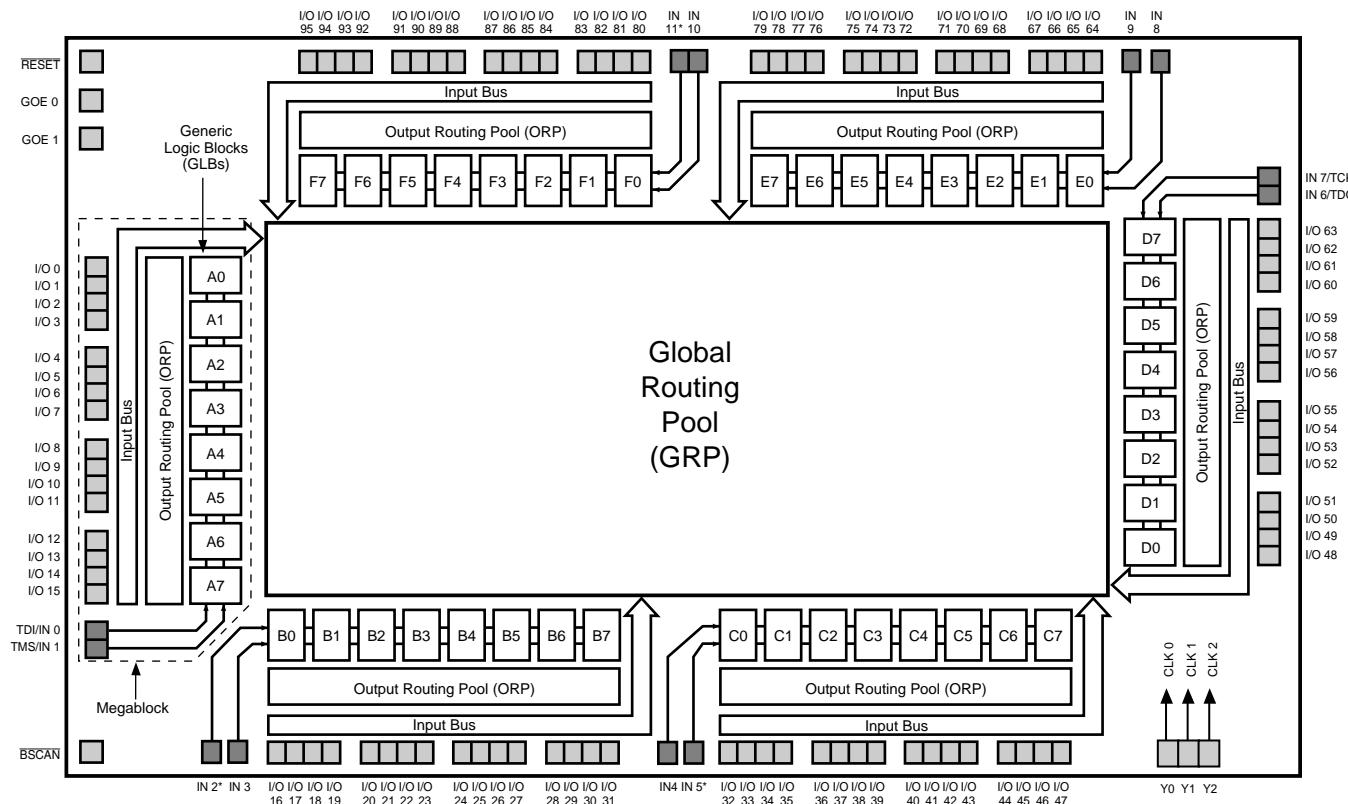
Description

The ispLSI 2192VL is a High Density Programmable Logic Device containing 192 Registers, nine Dedicated Input pins, three Dedicated Clock Input pins, two dedicated Global OE input pins and a Global Routing Pool (GRP). The GRP provides complete interconnectivity between all of these elements. The ispLSI 2192VL features in-system programmability through the Boundary Scan Test Access Port (TAP) and is 100% IEEE 1149.1 Boundary Scan Testable. The ispLSI 2192VL offers non-volatile reprogrammability of the logic, as well as the interconnect to provide truly reconfigurable systems.

The basic unit of logic on the ispLSI 2192VL device is the Generic Logic Block (GLB). The GLBs are labeled A0, A1 .. F7 (see Figure 1). There are a total of 48 GLBs in the ispLSI 2192VL device. Each GLB is made up of four macrocells. Each GLB has 18 inputs, a programmable AND/OR/Exclusive OR array, and four outputs which can be configured to be either combinatorial or registered. Inputs to the GLB come from the GRP and dedicated inputs. All of the GLB outputs are brought back into the GRP so that they can be connected to the inputs of any GLB on the device.

Functional Block Diagram

Figure 1. ispLSI 2192VL Functional Block Diagram



*Note: Dedicated Inputs 2, 5 and 11 are not available with 128-pin packages.

2192VL Block.eps

The 2192VL contains 96 I/O cells. Each I/O cell is directly connected to an I/O pin and can be individually programmed to be a combinatorial input, output or bi-directional I/O pin with 3-state control, and the output drivers can source 4mA or sink 8mA. Each output can be programmed independently for fast or slow output slew rate to minimize overall output switching noise. Device pins can be safely driven to 3.3V signal levels to support mixed-voltage systems.

Eight GLBs, 16 I/O cells, two dedicated inputs and an ORP are connected together to make a Megablock (see Figure 1). The outputs of the eight GLBs are connected to a set of 16 universal I/O cells by the ORPs. Each ispLSI 2192VL device contains six Megablocks.

The GRP has as its inputs, the outputs from all of the GLBs and all of the inputs from the bi-directional I/O cells. All of these signals are made available to the inputs of the GLBs. Delays through the GRP have been equalized to minimize timing skew.

Clocks in the ispLSI 2192VL device are selected using the dedicated clock pins. Three dedicated clock pins (Y0, Y1, Y2) or an asynchronous clock can be selected on a GLB basis. The asynchronous or Product Term clock can be generated in any GLB for its own clock.

Programmable Open-Drain Outputs

In addition to the standard output configuration, the outputs of the ispLSI 2192VL are individually programmable, either as a standard totem-pole output or an open-drain output. The totem-pole output drives the specified Voh and Vol levels, whereas the open-drain output drives only the specified Vol. The Voh level on the open-drain output depends on the external loading and pull-up. This output configuration is controlled by a programmable fuse. The default configuration is a totem-pole configuration. The open-drain/totem-pole option is selectable through the Lattice software tools.

Absolute Maximum Ratings¹

Supply Voltage V_{CC} -0.5 to +4.05V
 Input Voltage Applied -0.5 to +4.05V
 Off-State Output Voltage Applied -0.5 to +4.05V
 Storage Temperature -65 to 150°C
 Case Temp. with Power Applied -55 to 125°C
 Max. Junction Temp. (T_J) with Power Applied ... 150°C

1. Stresses above those listed under the "Absolute Maximum Ratings" may cause permanent damage to the device. Functional operation of the device at these or at any other conditions above those indicated in the operational sections of this specification is not implied (while programming, follow the programming specifications).

DC Recommended Operating Condition

SYMBOL	PARAMETER		MIN.	MAX.	UNITS
V_{CC}	Supply Voltage	Commercial T _A = 0°C to + 70°C	2.3	2.7	V
		Industrial T _A = -40°C to + 85°C	2.3	2.7	V
V_{IL}	Input Low Voltage		-0.3	0.7	V
V_{IH}	Input High Voltage		1.7	3.6	V

Table 2-0005/2192VL

Capacitance (T_A=25°C, f=1.0 MHz)

SYMBOL	PARAMETER	TYPICAL	UNITS	TEST CONDITIONS
C₁	Dedicated Input Capacitance	8	pf	V _{CC} = 2.5V, V _{IN} = 0.0V
C₂	I/O Capacitance	6	pf	V _{CC} = 2.5V, V _{I/O} = 0.0V
C₃	Clock and Global Output Enable Capacitance	10	pf	V _{CC} = 2.5V, V _Y = 0.0V

Table 2-0006/2192VL

Erase Reprogram Specifications

PARAMETER	MINIMUM	MAXIMUM	UNITS
Erase/Reprogram Cycles	10,000	—	Cycles

Table 2-0008/2192VL

Switching Test Conditions

Input Pulse Levels	GND to V_{CC}
Input Rise and Fall Time	$\leq 1.5\text{ns}$ 10% to 90%
Input Timing Reference Levels	$V_{CC}/2$
Output Timing Reference Levels	$V_{CC}/2$
Output Load	See Figure 2

3-state levels are measured 0.15V from steady-state active level.

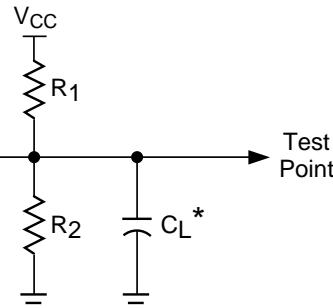
Table 2 - 0003/2192VL

Output Load Conditions (see Figure 2)

TEST CONDITION		R1	R2	CL
A		250Ω	218Ω	35pF
B	Active High	∞	218Ω	35pF
	Active Low	250Ω	∞	35pF
C	Active High to Z at $V_{OH}-0.15\text{V}$	∞	218Ω	5pF
	Active Low to Z at $V_{OL}+0.15\text{V}$	250Ω	∞	5pF

Table 2-0004/2192VL

Figure 2. Test Load



* C_L includes Test Fixture and Probe Capacitance.

0213A/2192VL

DC Electrical Characteristics

Over Recommended Operating Conditions

SYMBOL	PARAMETER	CONDITION	MIN.	TYP. ³	MAX.	UNITS
V_{OL}	Output Low Voltage	$I_{OL} = 100\mu\text{A}$	—	—	0.2	V
		$I_{OL} = 8\text{mA}$	—	—	0.4	V
V_{OH}	Output High Voltage	$I_{OH} = -100\mu\text{A}$	$V_{CC} - 0.2$	—	—	V
		$I_{OH} = -1\text{mA}$	2.0	—	—	V
		$I_{OH} = -4\text{mA}$	1.8	—	—	V
I_{IL}^5	Input or I/O Low Leakage Current	$0\text{V} \leq V_{IN} \leq V_{IL}(\text{Max.})$	—	—	-10	μA
I_{IH}	Input or I/O High Leakage Current	$V_{IH}(\text{min.}) \leq V_{IN} \leq 3.6\text{V}$	—	—	10	μA
$I_{IL\text{-isp}}$	BSCAN Input Pull-Up Current	$0\text{V} \leq V_{IN} \leq V_{IL}$	—	—	-150	μA
$I_{IL\text{-PU}}$	I/O Active Pull-Up Current	$0\text{V} \leq V_{IN} \leq V_{IL}$	—	—	-150	μA
I_{OS}^1	Output Short Circuit Current	$V_{CC} = 2.5\text{V}, V_{OUT} = 0.5\text{V}$	—	—	-100	mA
$I_{CC}^{2,4}$	Operating Power Supply Current	$V_{IL} = 0.0\text{V}, V_{IH} = 2.5\text{V}$ $f_{CLK} = 1\text{ MHz}$	—	175	—	mA

Table 2-0007/2192VL

- One output at a time for a maximum duration of one second. $V_{OUT} = 0.5\text{V}$ was selected to avoid test problems by tester ground degradation. Characterized but not 100% tested.
- Measured using 12 16-bit counters.
- Typical values are at $V_{CC} = 2.5\text{V}$ and $T_A = 25^\circ\text{C}$.
- Maximum I_{CC} varies widely with specific device configuration and operating frequency. Refer to Power Consumption section of this data sheet and Thermal Management section of the Lattice Semiconductor Data Book or CD-ROM to estimate maximum I_{CC} .
- With no pull-up resistors.

External Timing Parameters

Over Recommended Operating Conditions

PARAMETER	TEST ³ COND.	#	DESCRIPTION ¹	-150		-135		-100		UNITS
				MIN.	MAX.	MIN.	MAX.	MIN.	MAX.	
tpd1	A	1	Data Propagation Delay, 4PT Bypass, ORP Bypass	—	6.0	—	7.5	—	10.0	ns
tpd2	A	2	Data Propagation Delay	—	8.5	—	10.0	—	13.0	ns
fmax	A	3	Clock Frequency with Internal Feedback ²	150	—	135	—	100	—	MHz
fmax (Ext.)	—	4	Clock Frequency with External Feedback ($\frac{1}{tsu2 + tco1}$)	111	—	95	—	77	—	MHz
fmax (Tog.)	—	5	Clock Frequency, Max. Toggle	166	—	143	—	100	—	MHz
tsu1	—	6	GLB Reg. Setup Time before Clock, 4 PT Bypass	4.0	—	5.0	—	6.5	—	ns
tco1	A	7	GLB Reg. Clock to Output Delay, ORP Bypass	—	4.0	—	4.5	—	5.0	ns
th1	—	8	GLB Reg. Hold Time after Clock, 4 PT Bypass	0.0	—	0.0	—	0.0	—	ns
tsu2	—	9	GLB Reg. Setup Time before Clock	5.0	—	6.0	—	8.0	—	ns
tco2	A	10	GLB Reg. Clock to Output Delay	—	5.0	—	5.5	—	6.0	ns
th2	—	11	GLB Reg. Hold Time after Clock	0.0	—	0.0	—	0.0	—	ns
tr1	A	12	Ext. Reset Pin to Output Delay, ORP Bypass	—	6.0	—	8.0	—	13.5	ns
trw1	—	13	Ext. Reset Pulse Duration	5.0	—	5.5	—	6.5	—	ns
tptoeen	B	14	Input to Output Enable	—	10.0	—	12.0	—	15.0	ns
tptoedis	C	15	Input to Output Disable	—	10.0	—	12.0	—	15.0	ns
tgoeen	B	16	Global OE Output Enable	—	6.0	—	7.0	—	9.0	ns
tgoedis	C	17	Global OE Output Disable	—	6.0	—	7.0	—	9.0	ns
twh	—	18	External Synchronous Clock Pulse Duration, High	3.0	—	3.5	—	5.0	—	ns
twl	—	19	External Synchronous Clock Pulse Duration, Low	3.0	—	3.5	—	5.0	—	ns

1. Unless noted otherwise, all parameters use a GRP load of four, 20 PTXOR path, ORP and Y0 clock.

2. Standard 16-bit counter using GRP feedback.

3. Reference Switching Test Conditions section.

Table 2-0030C/2192VL

Internal Timing Parameters¹

Over Recommended Operating Conditions

PARAMETER	# ²	DESCRIPTION	-150		-135		-100		UNITS
			MIN.	MAX.	MIN.	MAX.	MIN.	MAX.	
Inputs									
tio	20	Input Buffer Delay	—	0.4	—	1.0	—	0.9	ns
tdin	21	Dedicated Input Delay	—	1.5	—	2.2	—	2.7	ns
GRP									
tgrp	22	GRP Delay	—	1.1	—	1.2	—	1.8	ns
GLB									
t4ptbpc	23	4 Product Term Bypass Path Delay (Combinatorial)	—	2.5	—	3.2	—	5.2	ns
t4ptbpr	24	4 Product Term Bypass Path Delay (Registered)	—	3.0	—	3.2	—	4.7	ns
t1ptxor	25	1 Product Term/XOR Path Delay	—	4.0	—	4.2	—	6.2	ns
t20ptxor	26	20 Product Term/XOR Path Delay	—	4.0	—	4.2	—	6.2	ns
txoradj	27	XOR Adjacent Path Delay ³	—	4.0	—	4.2	—	6.2	ns
tgbp	28	GLB Register Bypass Delay	—	0.0	—	0.5	—	1.0	ns
tgsu	29	GLB Register Setup Time before Clock	1.2	—	1.7	—	1.7	—	ns
tgh	30	GLB Register Hold Time after Clock	2.8	—	3.3	—	4.8	—	ns
tgco	31	GLB Register Clock to Output Delay	—	0.3	—	0.3	—	0.3	ns
tgro	32	GLB Register Reset to Output Delay	—	0.6	—	1.1	—	4.3	ns
tptre	33	GLB Product Term Reset to Register Delay	—	4.9	—	6.6	—	8.9	ns
tptoe	34	GLB Product Term Output Enable to I/O Cell Delay	—	5.0	—	5.8	—	7.4	ns
tptck	35	GLB Product Term Clock Delay	1.2	4.2	2.1	4.5	2.8	4.8	ns
ORP									
torp	36	ORP Delay	—	1.4	—	1.5	—	1.5	ns
torpbp	37	ORP Bypass Delay	—	0.4	—	0.5	—	0.5	ns
Outputs									
tob	38	Output Buffer Delay	—	1.6	—	1.6	—	1.6	ns
tsl	39	Output Slew Limited Delay Adder	—	2.0	—	2.0	—	2.0	ns
toen	40	I/O Cell OE to Output Enabled	—	3.5	—	4.0	—	4.9	ns
todis	41	I/O Cell OE to Output Disabled	—	3.5	—	4.0	—	4.9	ns
tgoe	42	Global Output Enable	—	2.5	—	3.0	—	4.1	ns
Clocks									
tgy0	43	Clock Delay, Y0 to Global GLB Clock Line (Ref. clock)	1.7	1.7	2.1	2.1	2.6	2.6	ns
tgy1/2	44	Clock Delay, Y1 or Y2 to Global GLB Clock Line	1.9	1.9	2.3	2.3	2.8	2.8	ns
Global Reset									
tgr	45	Global Reset to GLB	—	3.4	—	4.8	—	7.1	ns

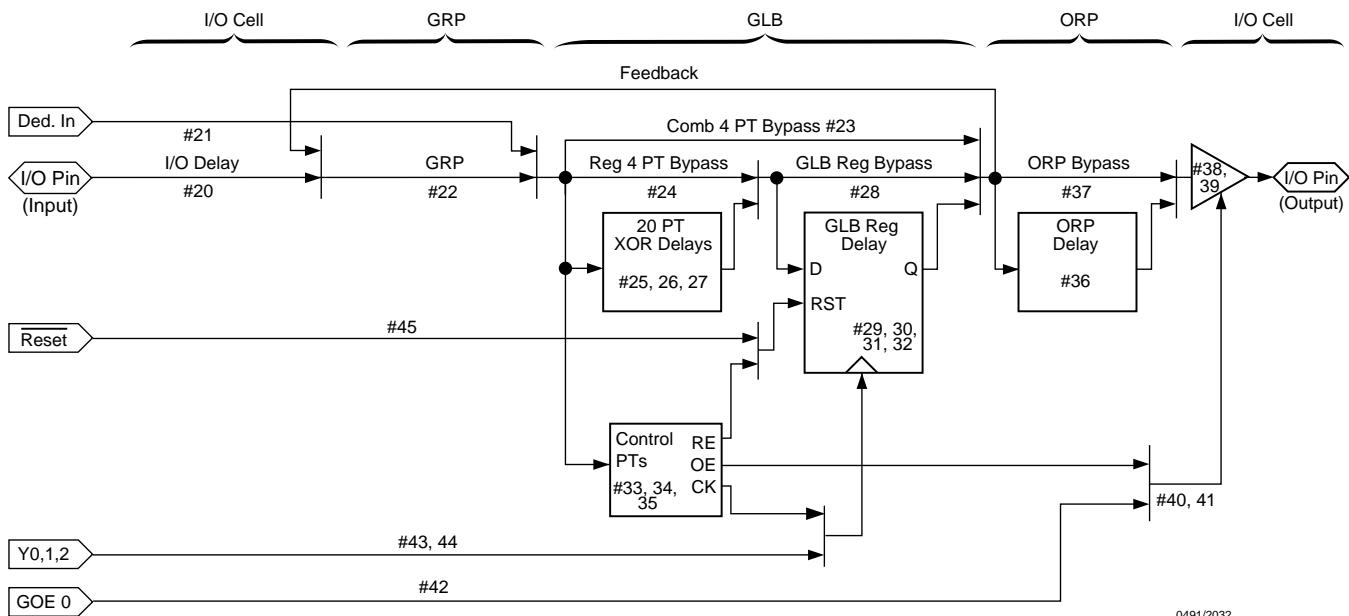
1. Internal Timing Parameters are not tested and are for reference only.

Table 2-0036/2192VL

2. Refer to Timing Model in this data sheet for further details.

3. The XOR adjacent path can only be used by hard macros.

ispLSI 2192VL Timing Model



Derivations of tsu, th and tco from the Product Term Clock

$$\begin{aligned}
 \text{tsu} &= \text{Logic} + \text{Reg su} - \text{Clock (min)} \\
 &= (\text{tio} + \text{tgrp} + \text{t20ptxor}) + (\text{tgtsu}) - (\text{tio} + \text{tgrp} + \text{tptck(min)}) \\
 &= (\#20 + \#22 + \#26) + (\#29) - (\#20 + \#22 + \#35) \\
 4.0\text{ns} &= (0.4 + 1.1 + 4.0) + (1.2) - (0.4 + 1.1 + 1.2)
 \end{aligned}$$

$$\begin{aligned}
 \text{th} &= \text{Clock (max)} + \text{Reg h} - \text{Logic} \\
 &= (\text{tio} + \text{tgrp} + \text{tptck(max)}) + (\text{tgh}) - (\text{tio} + \text{tgrp} + \text{t20ptxor}) \\
 &= (\#20 + \#22 + \#35) + (\#30) - (\#20 + \#22 + \#26) \\
 3.0\text{ns} &= (0.4 + 1.1 + 4.2) + (2.8) - (0.4 + 1.1 + 4.0)
 \end{aligned}$$

$$\begin{aligned}
 \text{tco} &= \text{Clock (max)} + \text{Reg co} + \text{Output} \\
 &= (\text{tio} + \text{tgrp} + \text{tptck(max)}) + (\text{tgco}) + (\text{torp} + \text{tob}) \\
 &= (\#20 + \#22 + \#35) + (\#31) + (\#36 + \#38) \\
 9.0\text{ns} &= (0.4 + 1.1 + 4.2) + (0.3) + (1.4 + 1.6)
 \end{aligned}$$

Note: Calculations are based upon timing specifications for the ispLSI 2192VL-150L.

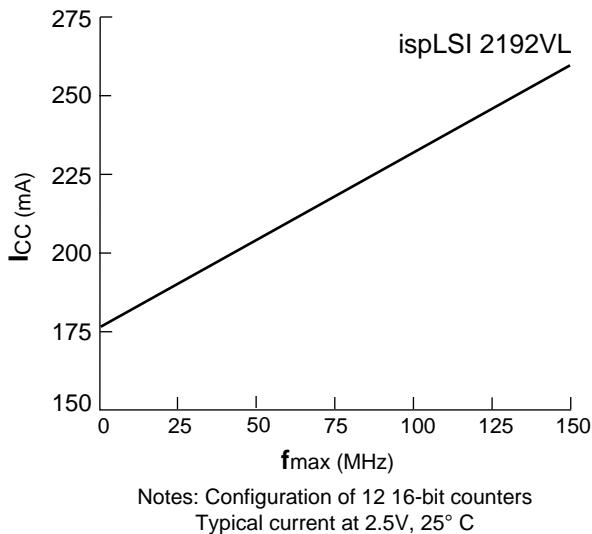
Table 2-0042/2192VL

Power Consumption

Power consumption in the ispLSI 2192VL device depends on two primary factors: the speed at which the device is operating and the number of Product Terms

used. Figure 3 shows the relationship between power and operating speed.

Figure 3. Typical Device Power Consumption vs fmax



I_{CC} can be estimated for the ispLSI 2192VL using the following equation:

$$I_{CC} = 12 + (\# \text{ of PTs} * 0.44) + (\# \text{ of nets} * \text{max freq} * 0.0029)$$

Where:

- # of PTs = Number of Product Terms used in design
- # of nets = Number of Signals used in device
- Max freq = Highest Clock Frequency to the device (in MHz)

The I_{CC} estimate is based on typical conditions ($V_{CC} = 2.5V$, room temperature) and an assumption of two GLB loads on average exists. These values are for estimates only. Since the value of I_{CC} is sensitive to operating conditions and the program in the device, the actual I_{CC} should be verified.

0127/2192VL

Signal Descriptions

Signal Name	Description
RESET	Active Low (0) Reset pin resets all the registers in the device.
GOE 0, GOE1	Global Output Enable input pins.
Y0, Y1, Y2	Dedicated Clock Input – These clock inputs are connected to one of the clock inputs of all the GLBs in the device.
BSCAN	Input – Dedicated in-system programming Boundary Scan enable input pin. This pin is brought low to enable the programming mode. The TMS, TDI, TDO and TCK controls become active.
TDI/IN 0	Input – This pin performs two functions. When <u>BSCAN</u> is logic low, it functions as a serial data input pin to load programming data into the device. When <u>BSCAN</u> is high, it functions as a dedicated input pin.
TCK/IN 7	Input – This pin performs two functions. When <u>BSCAN</u> is logic low, it functions as a clock pin for the Boundary Scan state machine. When <u>BSCAN</u> is high, it functions as a dedicated input pin.
TMS/IN 1	Input – This pin performs two functions. When <u>BSCAN</u> is logic low, it functions as a mode control pin for the Boundary Scan state machine. When <u>BSCAN</u> is high, it functions as a dedicated input pin.
TDO/IN 6	Output/Input – This pin performs two functions. When <u>BSCAN</u> is logic low, it functions as an output pin to read serial shift register data. When <u>BSCAN</u> is high, it functions as a dedicated input pin.
IN 2-5, IN 8-11	Dedicated Input Pins to the device.
GND	Ground (GND)
VCC	Vcc
NC ¹	No Connect
I/O	Input/Output Pins – These are the general purpose I/O pins used by the logic array.

1. NC pins are not to be connected to any active signals, VCC or GND.

Signal Locations

Signal Name	128-Pin TQFP	144-Ball fpBGA
RESET	15	G4
GOE 0, GOE 1	80, 17	F12, G2
Y0, Y1, Y2	14, 83, 78	F3, F10, G11
BSCAN	19	F1
TDI/IN 0	20	G3
TMS/IN 1	112	J6
TDO/IN 6	48	C7
TCK/IN 7	77	G12
IN 2-5, IN 8-11	—, 49, 82, —, 84, 113, 13, —	M7, J7, F9, G10, E12, B6, F2, E1
GND	18, 34, 50, 63, 79, 98, 111, 127	A1, A12, D4, D9, E5, E8, F6, F7, G6, G7, H5, H8, J4, J9, M1, M12
VCC	2, 16, 31, 47, 66, 81, 95, 114	B1, B12, E6, E7, F5, F8, G5, G8, H6, H7, L1, L12
NC ¹	—	K2

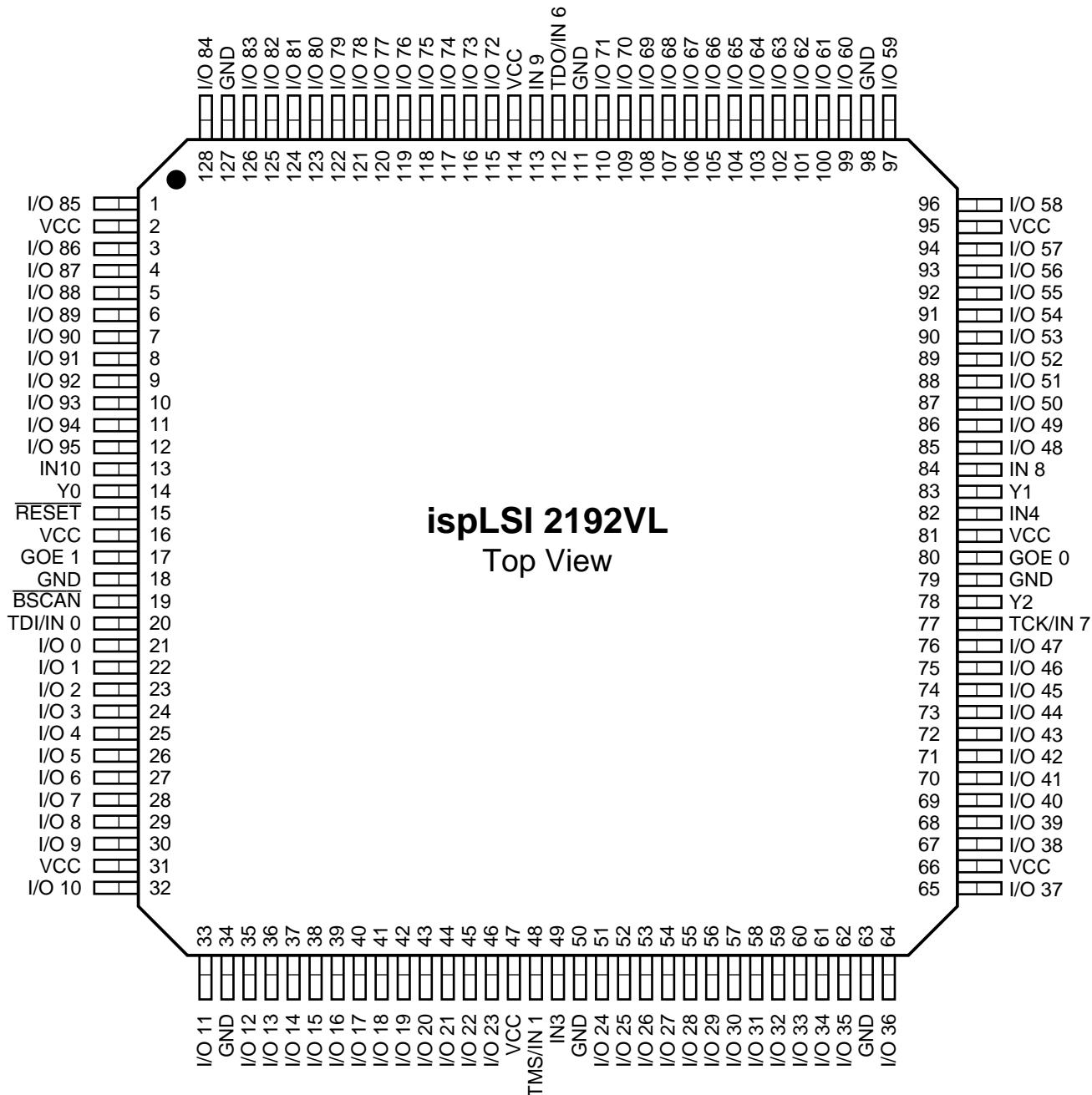
1. NC pins are not to be connected to any active signals, VCC or GND.

I/O Locations

Signal	128 TQFP	144 fpBGA	Signal	128 TQFP	144 fpBGA
I/O 0	21	H4	I/O 48	85	F11
I/O 1	22	G1	I/O 49	86	D12
I/O 2	23	H2	I/O 50	87	E9
I/O 3	24	H1	I/O 51	88	E10
I/O 4	25	H3	I/O 52	89	E11
I/O 5	26	J1	I/O 53	90	C12
I/O 6	27	J3	I/O 54	91	D10
I/O 7	28	K1	I/O 55	92	D11
I/O 8	29	J2	I/O 56	93	B11
I/O 9	30	M2	I/O 57	94	C11
I/O 10	32	L2	I/O 58	96	C10
I/O 11	33	L3	I/O 59	97	A11
I/O 12	35	K3	I/O 60	99	B10
I/O 13	36	M3	I/O 61	100	A10
I/O 14	37	L4	I/O 62	101	C9
I/O 15	38	K4	I/O 63	102	B9
I/O 16	39	M4	I/O 64	103	A9
I/O 17	40	J5	I/O 65	104	D8
I/O 18	41	M5	I/O 66	105	B8
I/O 19	42	K5	I/O 67	106	C8
I/O 20	43	L5	I/O 68	107	A8
I/O 21	44	M6	I/O 69	108	B7
I/O 22	45	L6	I/O 70	109	A7
I/O 23	46	K6	I/O 71	110	D7
I/O 24	51	L7	I/O 72	115	C6
I/O 25	52	K7	I/O 73	116	A6
I/O 26	53	J8	I/O 74	117	D6
I/O 27	54	M8	I/O 75	118	B5
I/O 28	55	L8	I/O 76	119	C5
I/O 29	56	K8	I/O 77	120	A5
I/O 30	57	M9	I/O 78	121	D5
I/O 31	58	L9	I/O 79	122	C4
I/O 32	59	K9	I/O 80	123	B4
I/O 33	60	M10	I/O 81	124	A4
I/O 34	61	L10	I/O 82	125	C3
I/O 35	62	M11	I/O 83	126	B3
I/O 36	64	K10	I/O 84	128	A3
I/O 37	65	K11	I/O 85	1	C2
I/O 38	67	L11	I/O 86	3	B2
I/O 39	68	K12	I/O 87	4	D2
I/O 40	69	J11	I/O 88	5	A2
I/O 41	70	J12	I/O 89	6	D3
I/O 42	71	J10	I/O 90	7	E2
I/O 43	72	H9	I/O 91	8	C1
I/O 44	73	H11	I/O 92	9	E3
I/O 45	74	H12	I/O 93	10	E4
I/O 46	75	H10	I/O 94	11	D1
I/O 47	76	G9	I/O 95	12	F4

Pin Configuration

ispLSI 2192VL 128-Pin TQFP Pinout Diagram



0124-2192VL

Pin Configuration

ispLSI 2192VL 144-Ball fpBGA Signal Diagram

	12	11	10	9	8	7	6	5	4	3	2	1
A	GND	I/O 59	I/O 61	I/O 64	I/O 68	I/O 70	I/O 73	I/O 77	I/O 81	I/O 84	I/O 88	GND
B	VCC	I/O 56	I/O 60	I/O 63	I/O 66	I/O 69	IN 9	I/O 75	I/O 80	I/O 83	I/O 86	VCC
C	I/O 53	I/O 57	I/O 58	I/O 62	I/O 67	TDO/ IN 6	I/O 72	I/O 76	I/O 79	I/O 82	I/O 85	I/O 91
D	I/O 49	I/O 55	I/O 54	GND	I/O 65	I/O 71	I/O 74	I/O 78	GND	I/O 89	I/O 87	I/O 94
E	IN 8	I/O 52	I/O 51	I/O 50	GND	VCC	VCC	GND	I/O 93	I/O 92	I/O 90	IN 11
F	GOE 0	I/O 48	Y1	IN 4	VCC	GND	GND	VCC	I/O 95	Y0	IN 10	BSCAN
G	TCK/ IN 7	Y2	IN 5	I/O 47	VCC	GND	GND	VCC	RESET	TDI/ IN 0	GOE 1	I/O 1
H	I/O 45	I/O 44	I/O 46	I/O 43	GND	VCC	VCC	GND	I/O 0	I/O 4	I/O 2	I/O 3
J	I/O 41	I/O 40	I/O 42	GND	I/O 26	IN 3	TMS/ IN 1	I/O 17	GND	I/O 6	I/O 8	I/O 5
K	I/O 39	I/O 37	I/O 36	I/O 32	I/O 29	I/O 25	I/O 23	I/O 19	I/O 15	I/O 12	NC ¹	I/O 7
L	VCC	I/O 38	I/O 34	I/O 31	I/O 28	I/O 24	I/O 22	I/O 20	I/O 14	I/O 11	I/O 10	VCC
M	GND	I/O 35	I/O 33	I/O 30	I/O 27	IN 2	I/O 21	I/O 18	I/O 16	I/O 13	I/O 9	GND

12 11 10 9 8 7 6 5 4 3 2 1

ispLSI 2192VL

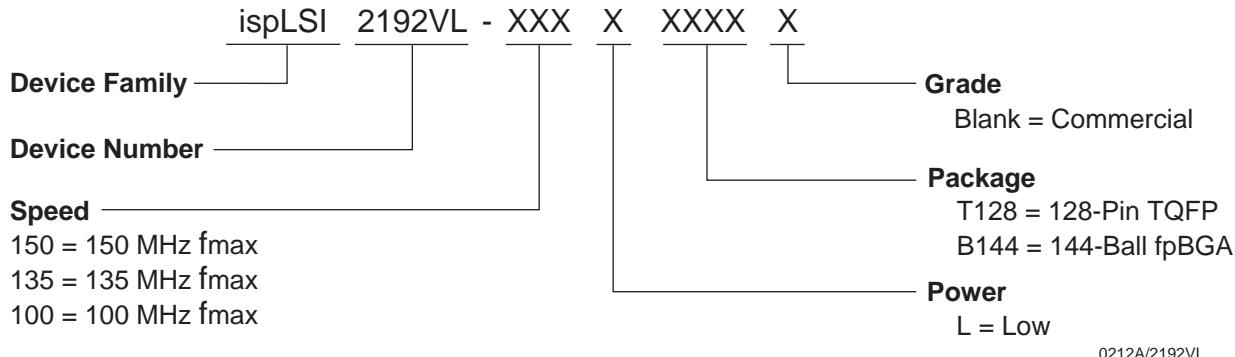
Bottom View

144-BGA/2192VL

¹NCs are not to be connected to any active signals, VCC or GND.

Note: Ball A1 indicator dot on top side of package.

Part Number Description



ispLSI 2192VL Ordering Information

COMMERCIAL

FAMILY	f _{max} (MHz)	t _{pd} (ns)	ORDERING NUMBER	PACKAGE
ispLSI	150	6.0	ispLSI 2192VL-150LT128	128-Pin TQFP
	150	6.0	ispLSI 2192VL-150LB144	144-Ball fpBGA
	135	7.5	ispLSI 2192VL-135LT128	128-Pin TQFP
	135	7.5	ispLSI 2192VL-135LB144	144-Ball fpBGA
	100	10	ispLSI 2192VL-100LT128	128-Pin TQFP
	100	10	ispLSI 2192VL-100LB144	144-Ball fpBGA

Table 2-0041C/2192VL